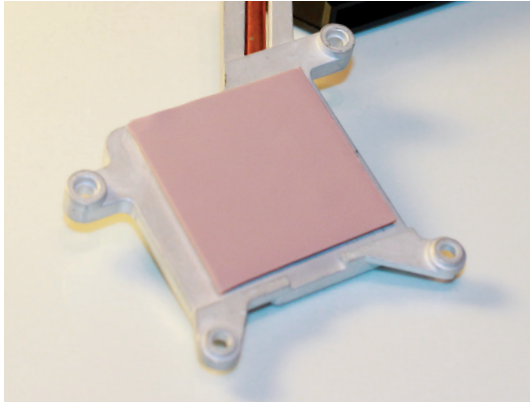


TG6050

Ultra Soft Thermal Conductive Pad



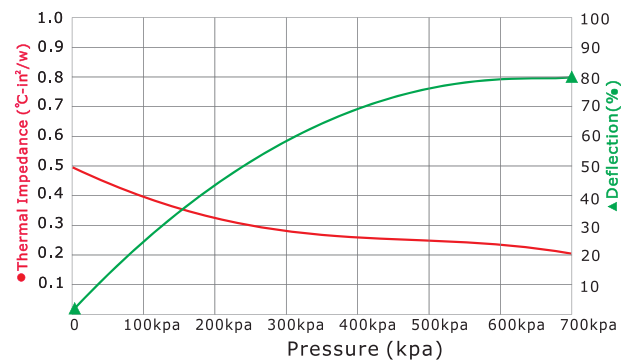
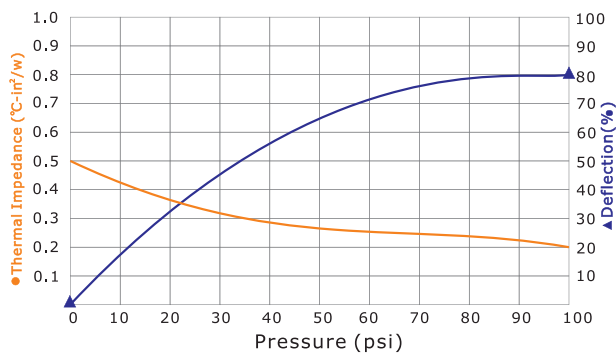
Features

- Superior thermal conductivity
- Highly compressible
- Naturally tacky
- Low Shore 00 hardness
- Low oil bleed
- Electrically insulating

Applications

- Electronic components: IC / CPU / MOS
- LED / M/B / P/S / Heat Sink / LCD-TV / Notebook PC / PC / Telecom Device / Wireless Hub etc....
- DDR II Module / DVD Applications / Hand-Set applications etc...

Thermal Resistance V.S Pressure V.S Deflection



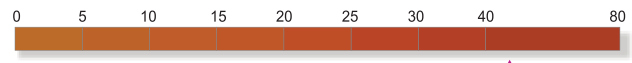
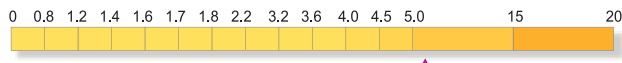
Properties

REACH Compliant

RoHS Compliant

Thermal Conductivity: 6.0 W/mK
(W/mK - Z Axis)

Hardness: 50 (Shore 00)
(Shore 00)



Testing sample thickness : 1.0 mm

In the thermal resistance vs pressure vs deflection charts TG6050 provides low thermal impedance. As the pressure increases the thermal impedance decreases. TG6050 provides good compliance and softness.

Property	TG6050	Unit	Tolerance	Test Method
Colour	Red	-	-	Visual
Thickness (Available thickness range)	0.5 - 2.0	mm	-	ASTM D374
	0.0197 - 0.0787	inch	-	ASTM D374
Thermal Conductivity	6	W/mK	-	ASTM D5470
Flammability Rating	V-0	-	-	UL 94
Dielectric Breakdown Voltage	13	kV/mm	-	ASTM D149
Weight Loss	<1	%	-	ASTM E595
Specific Gravity	3.2	g/cm ³	±0.2	ASTM D792
Working Temperature	-45 to 200	°C	-	-
Volume Resistance	>10 ¹²	Ohm-cm	-	ASTM D257
Elongation	50	%	±13	ASTM D412
Tensile Strength	0.5	Kgf/cm ²	±2	ASTM D412
Standard Shape	-	Sheets 320-320mm	-	-
Hardness	50	Shore 00	±5	ASTM D2240

Available with an adhesive backing

